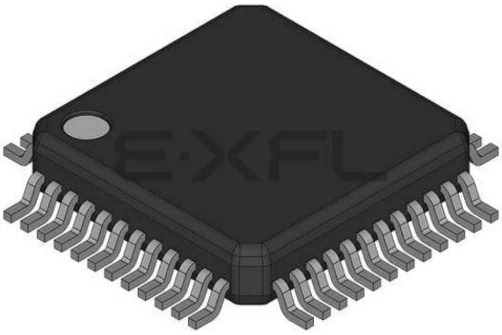
Freescale Semiconductor - MC9S08DN60CLF Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	39
Program Memory Size	60KB (60K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 16x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s08dn60clf

3.6 Stop Modes

One of two stop modes is entered upon execution of a STOP instruction when the STOPE bit in SOPT1 register is set. In both stop modes, all internal clocks are halted. The MCG module can be configured to leave the reference clocks running. See Chapter 8, “Multi-Purpose Clock Generator (S08MCGV1),” for more information.

Table 3-1 shows all of the control bits that affect stop mode selection and the mode selected under various conditions. The selected mode is entered following the execution of a STOP instruction.

Table 3-1. Stop Mode Selection

STOPE	ENBDM [1]	LVDE	LVDSE	PPDC	Stop Mode
0	x	x		x	Stop modes disabled; illegal opcode reset if STOP instruction executed
1	1	x		x	Stop3 with BDM enabled [2]
1	0	Both bits must be 1		x	Stop3 with voltage regulator active
1	0	Either bit a 0		0	Stop3
1	0	Either bit a 0		1	Stop2

[1] ENBDM is located in the BDCSCR, which is only accessible through BDC commands, see Section 16.4.1.1, “BDC Status and Control Register (BDCSCR)”.

[2] When in Stop3 mode with BDM enabled, The S_{IDD} will be near R_{IDD} levels because internal clocks are enabled.

3.6.1 Stop3 Mode

Stop3 mode is entered by executing a STOP instruction under the conditions as shown in Table 3-1. The states of all of the internal registers and logic, RAM contents, and I/O pin states are maintained.

Exit from stop3 is done by asserting $\overline{\text{RESET}}$ or an asynchronous interrupt pin. The asynchronous interrupt pins are IRQ, PIA0–PIA7, PIB0–PIB7, and PID0–PID7. Exit from stop3 can also be done by the low-voltage detect (LVD) reset, low-voltage warning (LVW) interrupt, ADC conversion complete interrupt, real-time clock (RTC) interrupt or SCI receiver interrupt.

If stop3 is exited by means of the $\overline{\text{RESET}}$ pin, the MCU will be reset and operation will resume after fetching the reset vector. Exit by means of an interrupt will result in the MCU fetching the appropriate interrupt vector.

3.6.1.1 LVD Enabled in Stop3 Mode

The LVD system is capable of generating either an interrupt or a reset when the supply voltage drops below the LVD voltage. If the LVD is enabled in stop (LVDE and LVDSE bits in SPMSC1 both set) at the time the CPU executes a STOP instruction, then the voltage regulator remains active during stop mode.

For the ADC to operate the LVD must be left enabled when entering stop3.

4.5.5 Sector Erase Abort

The sector erase abort operation will terminate the active sector erase operation so that other sectors are available for read and program operations without waiting for the sector erase operation to complete.

The sector erase abort command write sequence is as follows:

1. Write to any Flash or EEPROM address to start the command write sequence for the sector erase abort command. The address and data written are ignored.
2. Write the sector erase abort command, 0x47, to the FCMD register.
3. Clear the FCBEF flag in the FSTAT register by writing a 1 to FCBEF to launch the sector erase abort command.

If the sector erase abort command is launched resulting in the early termination of an active sector erase operation, the FACCERR flag will set once the operation completes as indicated by the FCCF flag being set. The FACCERR flag sets to inform the user that the Flash sector may not be fully erased and a new sector erase command must be launched before programming any location in that specific sector.

If the sector erase abort command is launched but the active sector erase operation completes normally, the FACCERR flag will not set upon completion of the operation as indicated by the FCCF flag being set. Therefore, if the FACCERR flag is not set after the sector erase abort command has completed, a sector being erased when the abort command was launched will be fully erased.

A flowchart to execute the sector erase abort operation is shown in Figure 4-4.

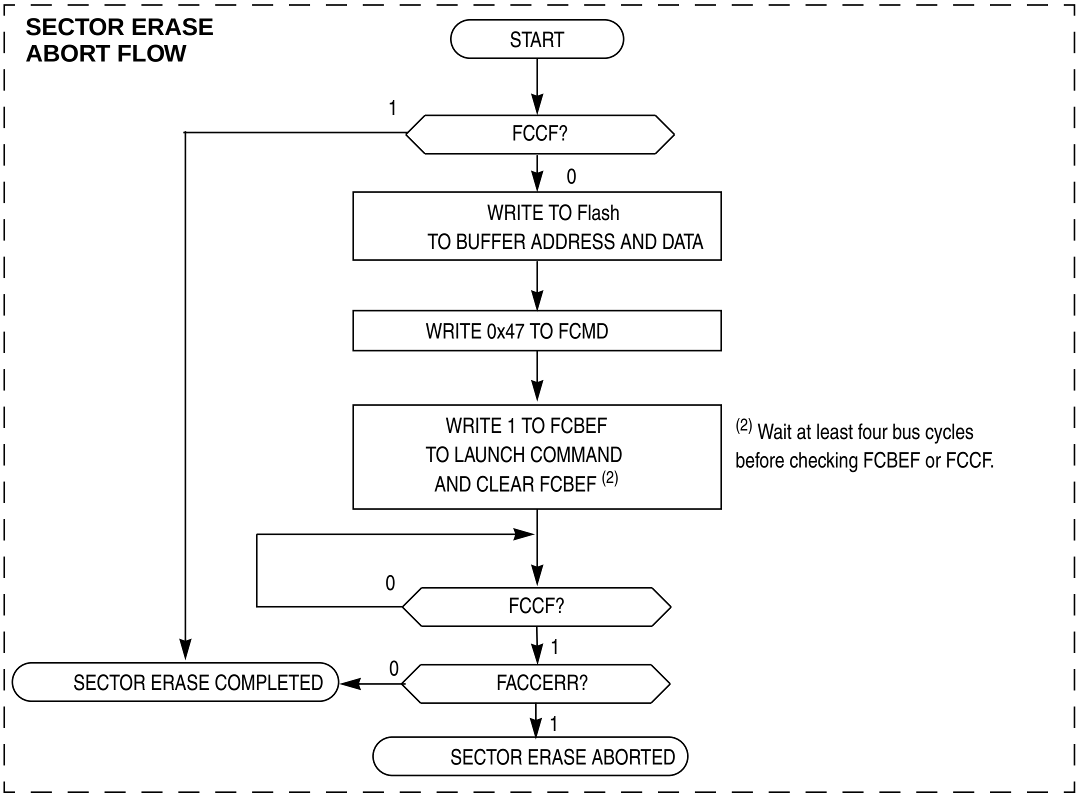


Figure 4-4. Sector Erase Abort Flowchart

which can be performed at the same time the Flash memory is programmed. The 1:0 state disengages security; the other three combinations engage security. Notice the erased state (1:1) makes the MCU secure. During development, whenever the Flash is erased, it is good practice to immediately program the SEC0 bit to 0 in NVOPT so SEC = 1:0. This would allow the MCU to remain unsecured after a subsequent reset.

The on-chip debug module cannot be enabled while the MCU is secure. The separate background debug controller can be used for background memory access commands, but the MCU cannot enter active background mode except by holding BKGD low at the rising edge of reset.

A user can choose to allow or disallow a security unlocking mechanism through an 8-byte backdoor security key. If the nonvolatile KEYEN bit in NVOPT/FOPT is 0, the backdoor key is disabled and there is no way to disengage security without completely erasing all Flash locations. If KEYEN is 1, a secure user program can temporarily disengage security by:

1. Writing 1 to KEYACC in the FCNFG register. This makes the Flash module interpret writes to the backdoor comparison key locations (NVBACKKEY through NVBACKKEY+7) as values to be compared against the key rather than as the first step in a Flash program or erase command.
2. Writing the user-entered key values to the NVBACKKEY through NVBACKKEY+7 locations. These writes must be performed in order starting with the value for NVBACKKEY and ending with NVBACKKEY+7. STHX must not be used for these writes because these writes cannot be performed on adjacent bus cycles. User software normally would get the key codes from outside the MCU system through a communication interface such as a serial I/O.
3. Writing 0 to KEYACC in the FCNFG register. If the 8-byte key that was written matches the key stored in the Flash locations, SEC bits are automatically changed to 1:0 and security will be disengaged until the next reset.

The security key can be written only from secure memory (either RAM, EEPROM, or Flash), so it cannot be entered through background commands without the cooperation of a secure user program.

The backdoor comparison key (NVBACKKEY through NVBACKKEY+7) is located in Flash memory locations in the nonvolatile register space so users can program these locations exactly as they would program any other Flash memory location. The nonvolatile registers are in the same 768-byte block of Flash as the reset and interrupt vectors, so block protecting that space also block protects the backdoor comparison key. Block protects cannot be changed from user application programs, so if the vector space is block protected, the backdoor security key mechanism cannot permanently change the block protect, security settings, or the backdoor key.

Security can always be disengaged through the background debug interface by taking these steps:

1. Disable any block protections by writing FPROT. FPROT can be written only with background debug commands, not from application software.
2. Mass erase Flash if necessary.
3. Blank check Flash. Provided Flash is completely erased, security is disengaged until the next reset.

   To avoid returning to secure mode after the next reset, program NVOPT so SEC = 1:0.

	7	6	5	4	3	2	1	0
R	KEYEN	FNORED	EPGMOD	0	0	0	SEC	
W	▨	▨	▨	▨	▨	▨	▨	▨
Reset	F	F	F	0	0	0	F	F

▨ = Unimplemented or Reserved F = loaded from nonvolatile location NVOPT during reset

Figure 4-6. Flash and EEPROM Options Register (FOPT)

Table 4-8. FOPT Register Field Descriptions

Field	Description
7 KEYEN	**Backdoor Key Mechanism Enable** — When this bit is 0, the backdoor key mechanism cannot be used to disengage security. The backdoor key mechanism is accessible only from user (secured) firmware. BDM commands cannot be used to write key comparison values that would unlock the backdoor key. For more detailed information about the backdoor key mechanism, refer to Section 4.5.9, "Security." 0 No backdoor key access allowed. 1 If user firmware writes an 8-byte value that matches the nonvolatile backdoor key (NVBACKKEY through NVBACKKEY+7 in that order), security is temporarily disengaged until the next MCU reset.
6 FNORED	**Vector Redirection Disable** — When this bit is 1, then vector redirection is disabled. 0 Vector redirection enabled. 1 Vector redirection disabled.
5 EPGMOD	**EEPROM Sector Mode** — When this bit is 0, each sector is split into two pages (4-byte mode). When this bit is 1, each sector is in a single page (8-byte mode). 0 Half of each EEPROM sector is in Page 0 and the other half is in Page 1. 1 Each sector is in a single page.
1:0 SEC	**Security State Code** — This 2-bit field determines the security state of the MCU as shown in Table 4-9. When the MCU is secure, the contents of RAM, EEPROM and Flash memory cannot be accessed by instructions from any unsecured source including the background debug interface. SEC changes to 1:0 after successful backdoor key entry or a successful blank check of Flash. For more detailed information about security, refer to Section 4.5.9, "Security."

Table 4-9. Security States[1]

SEC[1:0]	Description
0:0	secure
0:1	secure
1:0	unsecured
1:1	secure

[1] SEC changes to 1:0 after successful backdoor key entry or a successful blank check of Flash.

comprised of a power-on reset (POR) circuit and a LVD circuit with trip voltages for warning and detection. The LVD circuit is enabled when LVDE in SPMSC1 is set to 1. The LVD is disabled upon entering any of the stop modes unless LVDSE is set in SPMSC1. If LVDSE and LVDE are both set, then the MCU cannot enter stop2 (it will enter stop3 instead), and the current consumption in stop3 with the LVD enabled will be higher.

5.6.1 Power-On Reset Operation

When power is initially applied to the MCU, or when the supply voltage drops below the power-on reset rearm voltage level, V_{POR}, the POR circuit will cause a reset condition. As the supply voltage rises, the LVD circuit will hold the MCU in reset until the supply has risen above the low-voltage detection low threshold, V_{LVDL}. Both the POR bit and the LVD bit in SRS are set following a POR.

5.6.2 Low-Voltage Detection (LVD) Reset Operation

The LVD can be configured to generate a reset upon detection of a low-voltage condition by setting LVDRE to 1. The low-voltage detection threshold is determined by the LVDV bit. After an LVD reset has occurred, the LVD system will hold the MCU in reset until the supply voltage has risen above the low-voltage detection threshold. The LVD bit in the SRS register is set following either an LVD reset or POR.

5.6.3 Low-Voltage Warning (LVW) Interrupt Operation

The LVD system has a low-voltage warning flag to indicate to the user that the supply voltage is approaching the low-voltage condition. When a low-voltage warning condition is detected and is configured for interrupt operation (LVWIE set to 1), LVWF in SPMSC1 will be set and an LVW interrupt request will occur.

5.7 MCLK Output

The PTA0 pin is shared with the MCLK clock output. If the MCSEL bits are all zeroes, the MCLK clock is disabled. Setting any of the MCSEL bits causes the PTA0 pin to output a divided version of the internal MCU bus clock regardless of the state of the port data direction control bit for the pin. The divide ratio is determined by the MCSEL bits. The slew rate and drive strength for the pin are controlled by PTASE0 and PTADS0, respectively. The maximum clock output frequency is limited if slew rate control is enabled, see the electrical specifications for the maximum frequency under different conditions.

5.8.4 System Options Register 1 (SOPT1)

This high page register is a write-once register so only the first write after reset is honored. It can be read at any time. Any subsequent attempt to write to SOPT1 (intentionally or unintentionally) is ignored to avoid accidental changes to these sensitive settings. This register should be written during the user's reset initialization program to set the desired controls even if the desired settings are the same as the reset settings.

	7	6	5	4	3	2	1	0
R	COPT		STOPE	Reserved	IICPS	0	0	0
W						▨	▨	▨
Reset:	1	1	0	0	0	0	0	0

▨ = Unimplemented or Reserved

Figure 5-5. System Options Register 1 (SOPT1)

Table 5-5. SOPT1 Register Field Descriptions

Field	Description
7:6 COPT[1:0]	**COP Watchdog Timeout** — These write-once bits select the timeout period of the COP. COPT along with COPCLKS in SOPT2 defines the COP timeout period. See Table 5-6.
5 STOPE	**Stop Mode Enable** — This write-once bit is used to enable stop mode. If stop mode is disabled and a user program attempts to execute a STOP instruction, an illegal opcode reset is forced. 0 Stop mode disabled. 1 Stop mode enabled.
3 IICPS	**IIC Pin Select**— This write-once bit selects the location of the SCL and SDA pins of the IIC module. 0 SCL on PTF2, SDA on PTF3. 1 SCL on PTE4, SDA on PTE5.

Table 5-6. COP Configuration Options

Control Bits		Clock Source	COP Window[1] Opens (COPW = 1)	COP Overflow Count
COPCLKS	COPT[1:0]			
N/A	0:0	N/A	N/A	COP is disabled
0	0:1	1 kHz	N/A	2^5 cycles (32 ms[2])
0	1:0	1 kHz	N/A	2^8 cycles (256 ms[1])
0	1:1	1 kHz	N/A	2^{10} cycles (1.024 s[1])
1	0:1	Bus	6144 cycles	2^{13} cycles
1	1:0	Bus	49,152 cycles	2^{16} cycles
1	1:1	Bus	196,608 cycles	2^{18} cycles

[1] Windowed COP operation requires the user to clear the COP timer in the last 25% of the selected timeout period. This column displays the minimum number of clock counts required before the COP timer can be reset when in windowed COP mode (COPW = 1).

[2] Values shown in milliseconds based on t_{LPO} = 1 ms. See t_{LPO} in the appendix Section A.12.1, "Control Timing," for the tolerance of this value.

5.8.5 System Options Register 2 (SOPT2)

This high page register contains bits to configure MCU specific features on the MC9S08DN60 Series devices.

	7	6	5	4	3	2	1	0
R	COPCLKS[1]	COPW[1]	0	ADHTS	0	MCSEL		
W			▨		▨			
Reset:	0	0	0	0	0	0	0	0

▨ = Unimplemented or Reserved

Figure 5-6. System Options Register 2 (SOPT2)

[1] This bit can be written only one time after reset. Additional writes are ignored.

Table 5-7. SOPT2 Register Field Descriptions

Field	Description
7 COPCLKS	**COP Watchdog Clock Select** — This write-once bit selects the clock source of the COP watchdog. See Table 5-6 for details. 0 Internal 1-kHz clock is source to COP. 1 Bus clock is source to COP.
6 COPW	**COP Window** — This write-once bit selects the COP operation mode. When set, the 0x55-0xAA write sequence to the SRS register must occur in the last 25% of the selected period. Any write to the SRS register during the first 75% of the selected period will reset the MCU. 0 Normal COP operation. 1 Window COP operation.
4 ADHTS	**ADC Hardware Trigger Select** — This bit selects which hardware trigger initiates conversion for the analog to digital converter when the ADC hardware trigger is enabled (ADCTRG is set in ADCSC2 register). 0 Real Time Counter (RTC) overflow. 1 External Interrupt Request (IRQ) pin.
2:0 MCSEL	**MCLK Divide Select**— These bits enable the MCLK output on PTA0 pin and select the divide ratio for the MCLK output according to the formula below when the MCSEL bits are not equal to all zeroes. In case that the MCSEL bits are all zeroes, the MCLK output is disabled. MCLK frequency = Bus Clock frequency ÷ (2 * MCSEL)

6.5.4 Port D Registers

Port D is controlled by the registers listed below.

6.5.4.1 Port D Data Register (PTDD)

	7	6	5	4	3	2	1	0
R W	PTDD7	PTDD6	PTDD5	PTDD4	PTDD3	PTDD2	PTDD1	PTDD0
Reset:	0	0	0	0	0	0	0	0

Figure 6-24. Port D Data Register (PTDD)

Table 6-22. PTDD Register Field Descriptions

Field	Description
7:0 PTDD[7:0]	**Port D Data Register Bits** — For port D pins that are inputs, reads return the logic level on the pin. For port D pins that are configured as outputs, reads return the last value written to this register. Writes are latched into all bits of this register. For port D pins that are configured as outputs, the logic level is driven out the corresponding MCU pin. Reset forces PTDD to all 0s, but these 0s are not driven out the corresponding pins because reset also configures all port pins as high-impedance inputs with pull-ups/pull-downs disabled.

6.5.4.2 Port D Data Direction Register (PTDDD)

	7	6	5	4	3	2	1	0
R W	PTDDD7	PTDDD6	PTDDD5	PTDDD4	PTDDD3	PTDDD2	PTDDD1	PTDDD0
Reset:	0	0	0	0	0	0	0	0

Figure 6-25. Port D Data Direction Register (PTDDD)

Table 6-23. PTDDD Register Field Descriptions

Field	Description
7:0 PTDDD[7:0]	**Data Direction for Port D Bits** — These read/write bits control the direction of port D pins and what is read for PTDD reads. 0 Input (output driver disabled) and reads return the pin value. 1 Output driver enabled for port D bit n and PTDD reads return the contents of PTDDn.

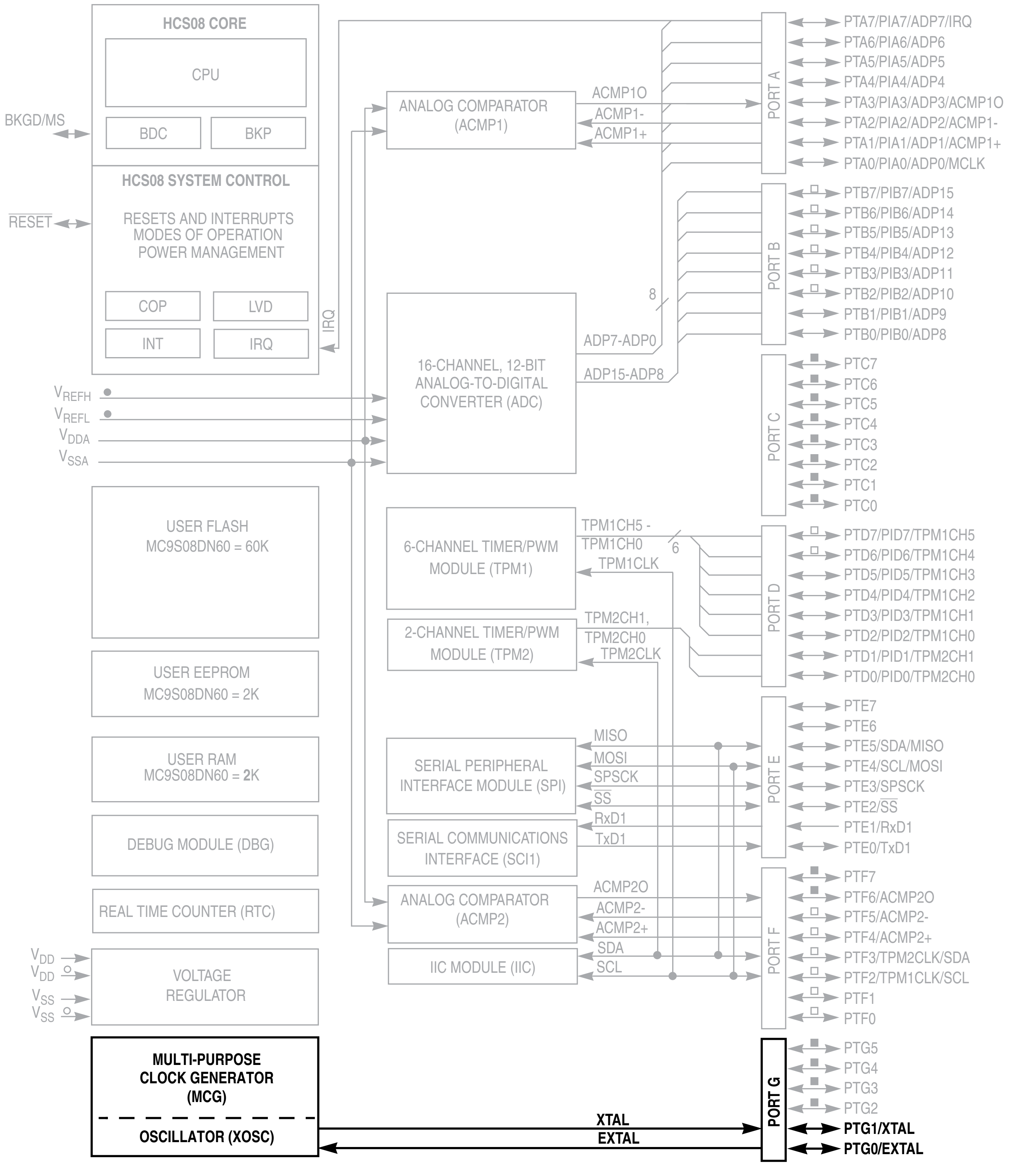
Table 7-3. Opcode Map (Sheet 2 of 2)

Bit-Manipulation		Branch	Read-Modify-Write					Control		Register/Memory					
						9E60 6 NEG 3 SP1							9ED0 5 SUB 4 SP2	9EE0 4 SUB 3 SP1	
						9E61 6 CBEQ 4 SP1							9ED1 5 CMP 4 SP2	9EE1 4 CMP 3 SP1	
													9ED2 5 SBC 4 SP2	9EE2 4 SBC 3 SP1	
						9E63 6 COM 3 SP1							9ED3 5 CPX 4 SP2	9EE3 4 CPX 3 SP1	9EF3 6 CPHX 3 SP1
						9E64 6 LSR 3 SP1							9ED4 5 AND 4 SP2	9EE4 4 AND 3 SP1	
													9ED5 5 BIT 4 SP2	9EE5 4 BIT 3 SP1	
						9E66 6 ROR 3 SP1							9ED6 5 LDA 4 SP2	9EE6 4 LDA 3 SP1	
						9E67 6 ASR 3 SP1							9ED7 5 STA 4 SP2	9EE7 4 STA 3 SP1	
						9E68 6 LSL 3 SP1							9ED8 5 EOR 4 SP2	9EE8 4 EOR 3 SP1	
						9E69 6 ROL 3 SP1							9ED9 5 ADC 4 SP2	9EE9 4 ADC 3 SP1	
						9E6A 6 DEC 3 SP1							9EDA 5 ORA 4 SP2	9EEA 4 ORA 3 SP1	
						9E6B 8 DBNZ 4 SP1							9EDB 5 ADD 4 SP2	9EEB 4 ADD 3 SP1	
						9E6C 6 INC 3 SP1									
						9E6D 5 TST 3 SP1									
										9EAE 5 LDHX 2 IX	9EBE 6 LDHX 4 IX2	9ECE 5 LDHX 3 IX1	9EDE 5 LDX 4 SP2	9EEE 4 LDX 3 SP1	9EFE 5 LDHX 3 SP1
						9E6F 6 CLR 3 SP1							9EDF 5 STX 4 SP2	9EEF 4 STX 3 SP1	9EFF 5 STHX 3 SP1

INH	Inherent	REL	Relative	SP1	Stack Pointer, 8-Bit Offset
IMM	Immediate	IX	Indexed, No Offset	SP2	Stack Pointer, 16-Bit Offset
DIR	Direct	IX1	Indexed, 8-Bit Offset	IX+	Indexed, No Offset with Post Increment
EXT	Extended	IX2	Indexed, 16-Bit Offset		
DD	DIR to DIR	IMD	IMM to DIR	IX1+	Indexed, 1-Byte Offset with Post Increment
IX+D	IX+ to DIR	DIX+	DIR to IX+		

Note: All Sheet 2 Opcodes are Preceded by the Page 2 Prebyte (9E)

Prebyte (9E) and Opcode in Hexadecimal	9E60 6	HCS08 Cycles
	NEG	Instruction Mnemonic
Number of Bytes	3 SP1	Addressing Mode



● - V_{REFH}/V_{REFL} internally connected to V_{DDA}/V_{SSA} in 48-pin and 32-pin packages
○ - V_{DD} and V_{SS} pins are each internally connected to two pads in 32-pin package

■ - Pin not connected in 48-pin and 32-pin packages
□ - Pin not connected in 32-pin package

Figure 8-1. MC9S08DN60 Block Diagram

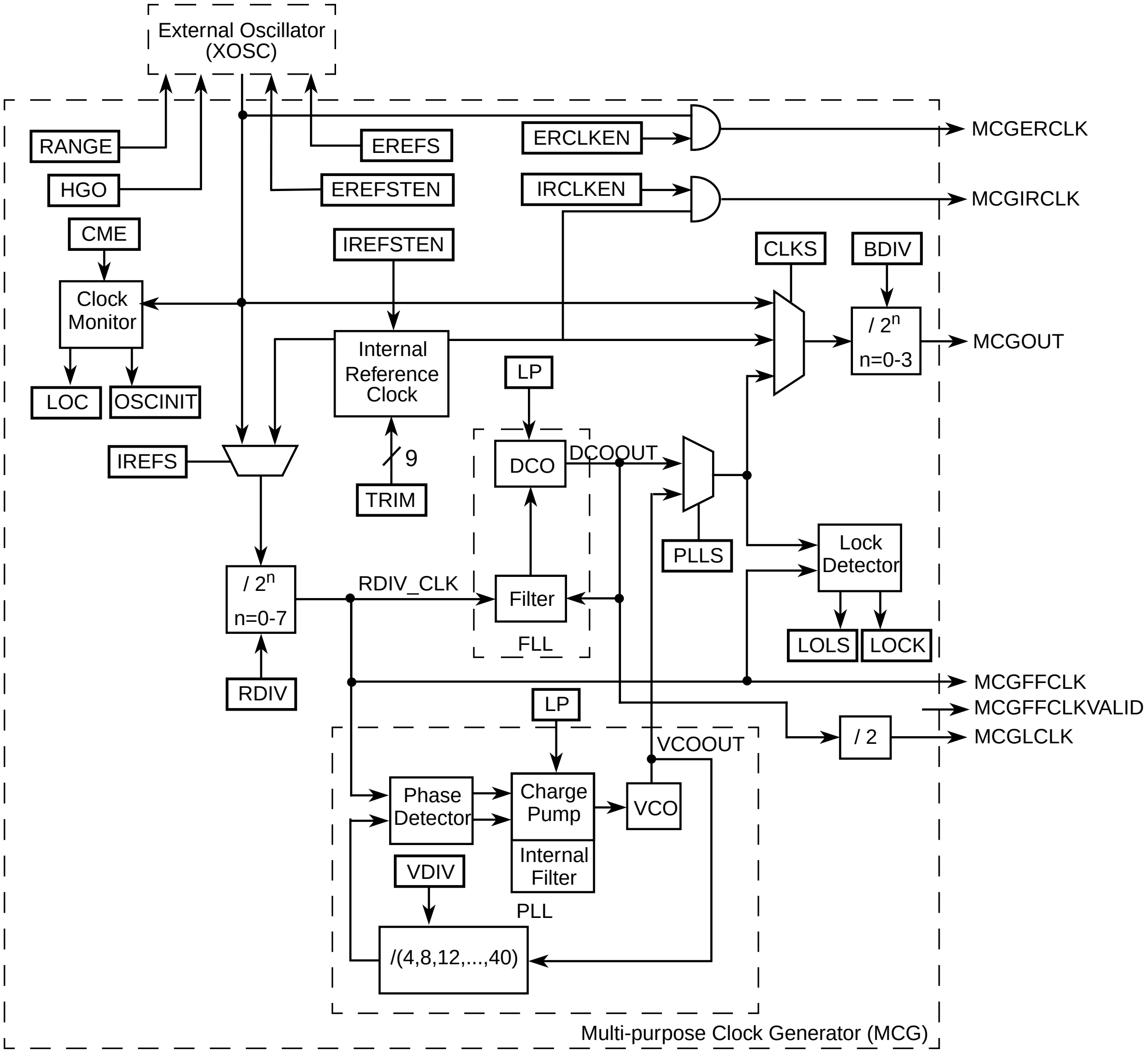


Figure 8-2. Multi-Purpose Clock Generator (MCG) Block Diagram

4. Lastly, FBI transitions into BLPI mode.
   a) MCGC2 = 0x08 (%00001000)
      – LP (bit 3) in MCGSC is 1

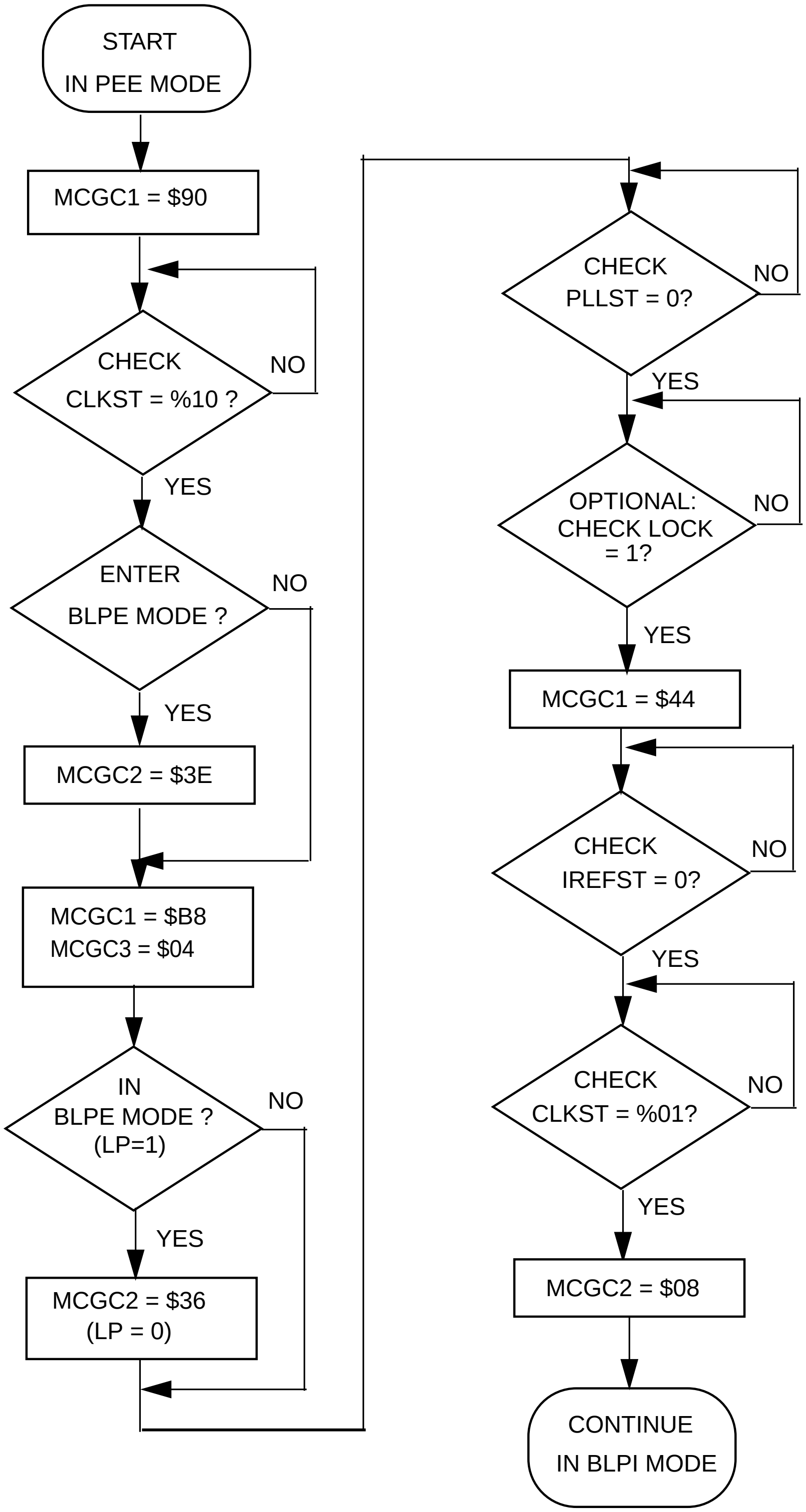
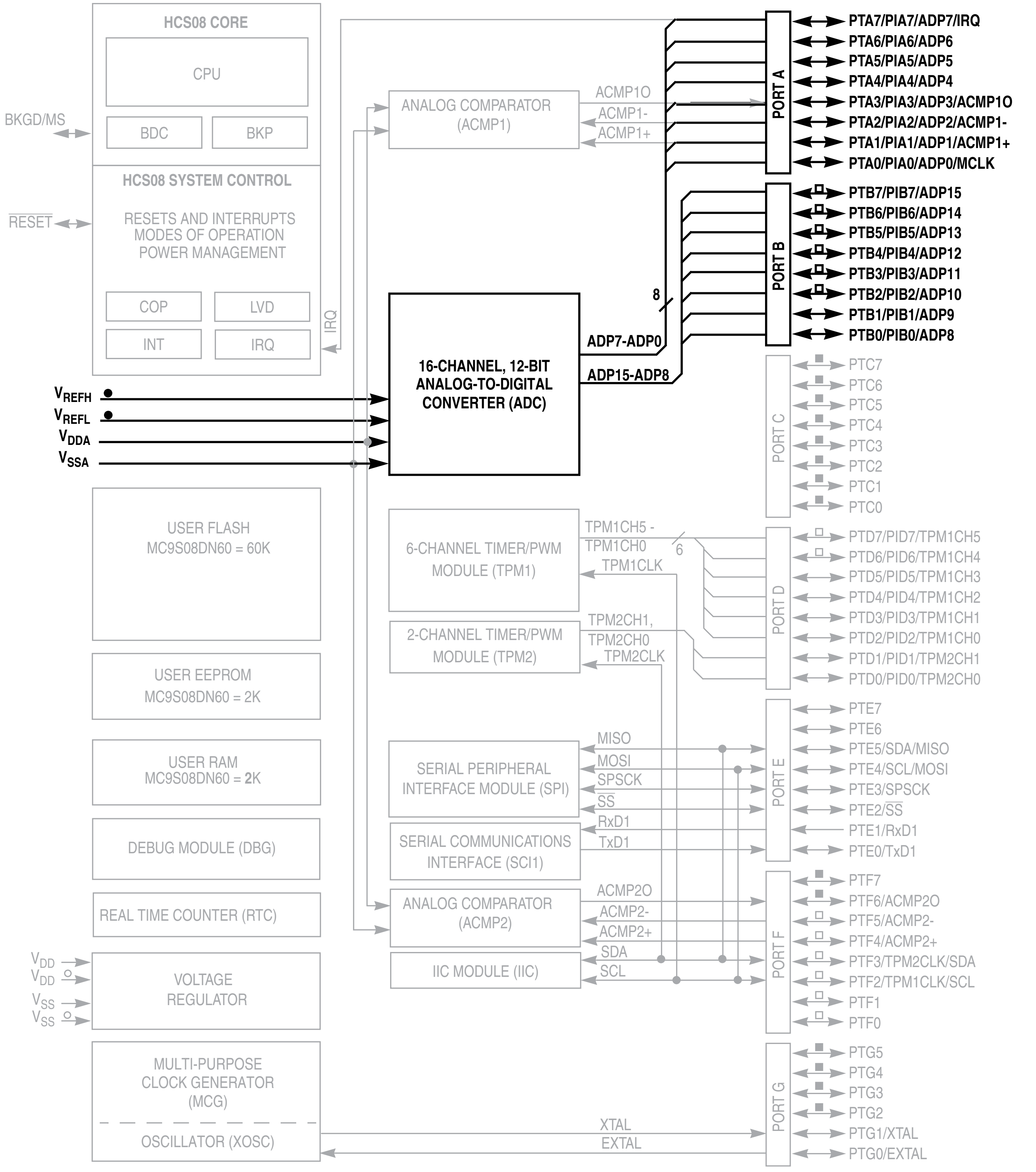


Figure 8-10. Flowchart of PEE to BLPI Mode Transition using a 4 MHz crystal



● - V_{REFH}/V_{REFL} internally connected to V_{DDA}/V_{SSA} in 48-pin and 32-pin packages

○ - V_{DD} and V_{SS} pins are each internally connected to two pads in 32-pin package

■ - Pin not connected in 48-pin and 32-pin packages

□ - Pin not connected in 32-pin package

Figure 10-1. MC9S08DN60 Block Diagram Emphasizing the ADC Module and Pins

10.1.6 Features

Features of the ADC module include:

- Linear successive approximation algorithm with 12-bit resolution
- Up to 28 analog inputs
- Output formatted in 12-, 10-, or 8-bit right-justified unsigned format
- Single or continuous conversion (automatic return to idle after single conversion)
- Configurable sample time and conversion speed/power
- Conversion complete flag and interrupt
- Input clock selectable from up to four sources
- Operation in wait or stop3 modes for lower noise operation
- Asynchronous clock source for lower noise operation
- Selectable asynchronous hardware conversion trigger
- Automatic compare with interrupt for less-than, or greater-than or equal-to, programmable value
- Temperature sensor

10.1.7 ADC Module Block Diagram

Figure 10-2 provides a block diagram of the ADC module.

Table 10-12. APCTL3 Register Field Descriptions

Field	Description
7 ADPC23	ADC Pin Control 23. ADPC23 controls the pin associated with channel AD23. 0 AD23 pin I/O control enabled 1 AD23 pin I/O control disabled
6 ADPC22	ADC Pin Control 22. ADPC22 controls the pin associated with channel AD22. 0 AD22 pin I/O control enabled 1 AD22 pin I/O control disabled
5 ADPC21	ADC Pin Control 21. ADPC21 controls the pin associated with channel AD21. 0 AD21 pin I/O control enabled 1 AD21 pin I/O control disabled
4 ADPC20	ADC Pin Control 20. ADPC20 controls the pin associated with channel AD20. 0 AD20 pin I/O control enabled 1 AD20 pin I/O control disabled
3 ADPC19	ADC Pin Control 19. ADPC19 controls the pin associated with channel AD19. 0 AD19 pin I/O control enabled 1 AD19 pin I/O control disabled
2 ADPC18	ADC Pin Control 18. ADPC18 controls the pin associated with channel AD18. 0 AD18 pin I/O control enabled 1 AD18 pin I/O control disabled
1 ADPC17	ADC Pin Control 17. ADPC17 controls the pin associated with channel AD17. 0 AD17 pin I/O control enabled 1 AD17 pin I/O control disabled
0 ADPC16	ADC Pin Control 16. ADPC16 controls the pin associated with channel AD16. 0 AD16 pin I/O control enabled 1 AD16 pin I/O control disabled

10.4 Functional Description

The ADC module is disabled during reset or when the ADCH bits are all high. The module is idle when a conversion has completed and another conversion has not been initiated. When idle, the module is in its lowest power state.

The ADC can perform an analog-to-digital conversion on any of the software selectable channels. In 12-bit and 10-bit mode, the selected channel voltage is converted by a successive approximation algorithm into a 12-bit digital result. In 8-bit mode, the selected channel voltage is converted by a successive approximation algorithm into a 9-bit digital result.

When the conversion is completed, the result is placed in the data registers (ADCRH and ADCRL). In 10-bit mode, the result is rounded to 10 bits and placed in the data registers (ADCRH and ADCRL). In 8-bit mode, the result is rounded to 8 bits and placed in ADCRL. The conversion complete flag (COCO) is then set and an interrupt is generated if the conversion complete interrupt has been enabled (AIEN = 1).

The ADC module has the capability of automatically comparing the result of a conversion with the contents of its compare registers. The compare function is enabled by setting the ACFE bit and operates with any of the conversion modes and configurations.

Table 12-7. SPIS Register Field Descriptions

Field	Description
7 SPRF	**SPI Read Buffer Full Flag** — SPRF is set at the completion of an SPI transfer to indicate that received data may be read from the SPI data register (SPID). SPRF is cleared by reading SPRF while it is set, then reading the SPI data register. 0 No data available in the receive data buffer 1 Data available in the receive data buffer
5 SPTEF	**SPI Transmit Buffer Empty Flag** — This bit is set when there is room in the transmit data buffer. It is cleared by reading SPIS with SPTEF set, followed by writing a data value to the transmit buffer at SPID. SPIS must be read with SPTEF = 1 before writing data to SPID or the SPID write will be ignored. SPTEF generates an SPTEF CPU interrupt request if the SPTIE bit in the SPIC1 is also set. SPTEF is automatically set when a data byte transfers from the transmit buffer into the transmit shift register. For an idle SPI (no data in the transmit buffer or the shift register and no transfer in progress), data written to SPID is transferred to the shifter almost immediately so SPTEF is set within two bus cycles allowing a second 8-bit data value to be queued into the transmit buffer. After completion of the transfer of the value in the shift register, the queued value from the transmit buffer will automatically move to the shifter and SPTEF will be set to indicate there is room for new data in the transmit buffer. If no new data is waiting in the transmit buffer, SPTEF simply remains set and no data moves from the buffer to the shifter. 0 SPI transmit buffer not empty 1 SPI transmit buffer empty
4 MODF	**Master Mode Fault Flag** — MODF is set if the SPI is configured as a master and the slave select input goes low, indicating some other SPI device is also configured as a master. The $\overline{SS}$ pin acts as a mode fault error input only when MSTR = 1, MODFEN = 1, and SSOE = 0; otherwise, MODF will never be set. MODF is cleared by reading MODF while it is 1, then writing to SPI control register 1 (SPIC1). 0 No mode fault error 1 Mode fault error detected

12.4.5 SPI Data Register (SPID)

	7	6	5	4	3	2	1	0
R W	Bit 7	6	5	4	3	2	1	Bit 0
Reset	0	0	0	0	0	0	0	0

Figure 12-9. SPI Data Register (SPID)

Reads of this register return the data read from the receive data buffer. Writes to this register write data to the transmit data buffer. When the SPI is configured as a master, writing data to the transmit data buffer initiates an SPI transfer.

Data should not be written to the transmit data buffer unless the SPI transmit buffer empty flag (SPTEF) is set, indicating there is room in the transmit buffer to queue a new transmit byte.

Data may be read from SPID any time after SPRF is set and before another transfer is finished. Failure to read the data out of the receive data buffer before a new transfer ends causes a receive overrun condition and the data from the new transfer is lost.

Figure 16-4 shows the host receiving a logic 0 from the target HCS08 MCU. Because the host is asynchronous to the target MCU, there is a 0-to-1 cycle delay from the host-generated falling edge on BKGD to the start of the bit time as perceived by the target MCU. The host initiates the bit time but the target HCS08 finishes it. Because the target wants the host to receive a logic 0, it drives the BKGD pin low for 13 BDC clock cycles, then briefly drives it high to speed up the rising edge. The host samples the bit level about 10 cycles after starting the bit time.

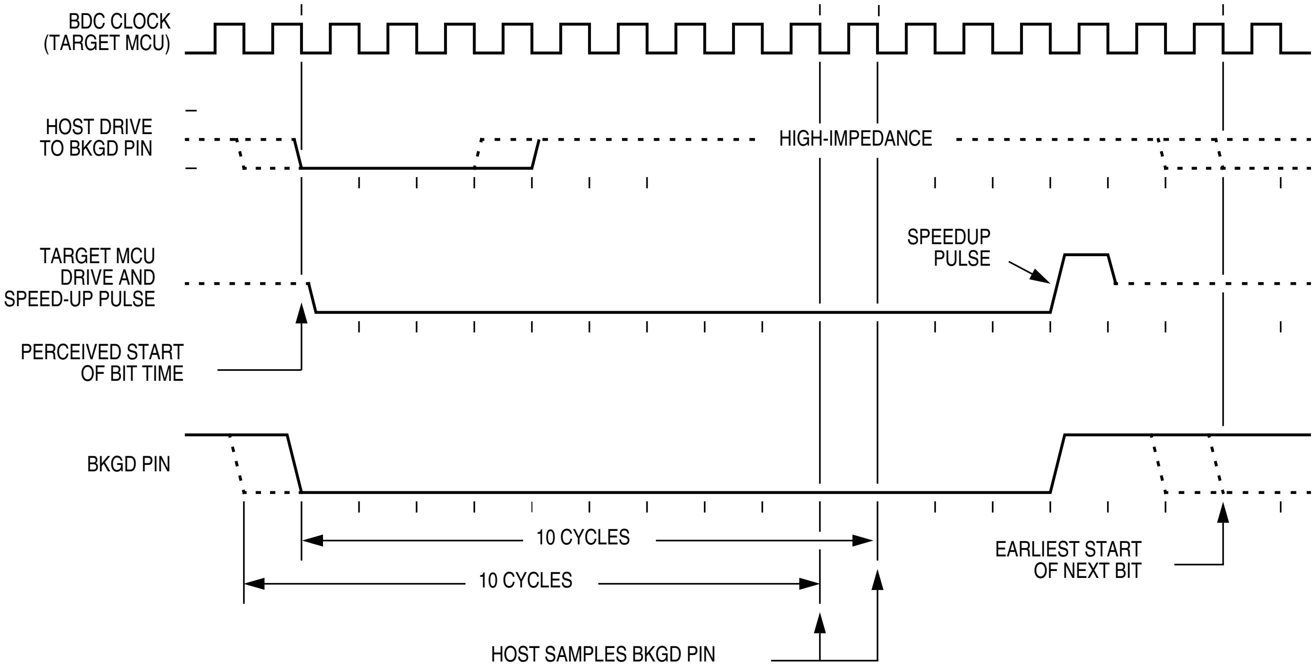


Figure 16-4. BDM Target-to-Host Serial Bit Timing (Logic 0)

Table 16-2. BDCSCR Register Field Descriptions (continued)

Field	Description
2 WS	**Wait or Stop Status** — When the target CPU is in wait or stop mode, most BDC commands cannot function. However, the BACKGROUND command can be used to force the target CPU out of wait or stop and into active background mode where all BDC commands work. Whenever the host forces the target MCU into active background mode, the host should issue a READ_STATUS command to check that BDMACT = 1 before attempting other BDC commands. 0 Target CPU is running user application code or in active background mode (was not in wait or stop mode when background became active) 1 Target CPU is in wait or stop mode, or a BACKGROUND command was used to change from wait or stop to active background mode
1 WSF	**Wait or Stop Failure Status** — This status bit is set if a memory access command failed due to the target CPU executing a wait or stop instruction at or about the same time. The usual recovery strategy is to issue a BACKGROUND command to get out of wait or stop mode into active background mode, repeat the command that failed, then return to the user program. (Typically, the host would restore CPU registers and stack values and re-execute the wait or stop instruction.) 0 Memory access did not conflict with a wait or stop instruction 1 Memory access command failed because the CPU entered wait or stop mode
0 DVF	**Data Valid Failure Status** — This status bit is not used in the MC9S08DN60 Series because it does not have any slow access memory. 0 Memory access did not conflict with a slow memory access 1 Memory access command failed because CPU was not finished with a slow memory access

16.4.1.2 BDC Breakpoint Match Register (BDCBKPT)

This 16-bit register holds the address for the hardware breakpoint in the BDC. The BKPTEN and FTS control bits in BDCSCR are used to enable and configure the breakpoint logic. Dedicated serial BDC commands (READ_BKPT and WRITE_BKPT) are used to read and write the BDCBKPT register but is not accessible to user programs because it is not located in the normal memory map of the MCU. Breakpoints are normally set while the target MCU is in active background mode before running the user application program. For additional information about setup and use of the hardware breakpoint logic in the BDC, refer to Section 16.2.4, “BDC Hardware Breakpoint.”

16.4.2 System Background Debug Force Reset Register (SBDFR)

This register contains a single write-only control bit. A serial background mode command such as WRITE_BYTE must be used to write to SBDFR. Attempts to write this register from a user program are ignored. Reads always return 0x00.

A.6 DC Characteristics

This section includes information about power supply requirements, I/O pin characteristics, and power supply current in various operating modes.

Table A-6. DC Characteristics

Num	C	Characteristic	Symbol	Condition	Min	Typ[1]	Max	Unit
1	—	Operating Voltage	V_{DD}		2.7	—	5.5	V
2	P	Output high voltage All I/O pins, low-drive strength	V_{OH}	5 V, I_{Load} = –2 mA	V_{DD} – 1.5	—	—	V
	C			3 V, I_{Load} = –0.6 mA	V_{DD} – 1.5	—	—	
	C			5 V, I_{Load} = –0.4 mA	V_{DD} – 0.8	—	—	
	C			3 V, I_{Load} = –0.24 mA	V_{DD} – 0.8	—	—	
	P	All I/O pins, high-drive strength		5 V, I_{Load} = –10 mA	V_{DD} – 1.5	—	—	
	C			3 V, I_{Load} = –3 mA	V_{DD} – 1.5	—	—	
	C			5 V, I_{Load} = –2 mA	V_{DD} – 0.8	—	—	
	C			3 V, I_{Load} = –0.4 mA	V_{DD} – 0.8	—	—	
3	C	Output high current Max total I_{OH} for all ports	I_{OHT}	5 V	0	—	-100	mA
				3 V	0	—	-60	
4	P	Output low voltage All I/O pins, low-drive strength	V_{OL}	5 V, I_{Load} = 2 mA	—	—	1.5	V
	C			3 V, I_{Load} = 0.6 mA	—	—	1.5	
	C			5 V, I_{Load} = 0.4 mA	—	—	0.8	
	C			3 V, I_{Load} = 0.24 mA	—	—	0.8	
	P	All I/O pins, high-drive strength		5 V, I_{Load} = 10 mA	—	—	1.5	
	C			3 V, I_{Load} = 3 mA	—	—	1.5	
	C			5 V, I_{Load} = 2 mA	—	—	0.8	
	C			3 V, I_{Load} = 0.4 mA	—	—	0.8	
5	C	Output low current Max total I_{OL} for all ports	I_{OLT}	5 V	0	—	100	mA
				3 V	0	—	60	
6	C	Input high voltage; all digital inputs	V_{IH}	5V	0.65 x V_{DD}	—	—	V
7	C	Input low voltage; all digital inputs	V_{IL}	5V	—	—	0.35 x V_{DD}	
8	C	Input hysteresis	V_{hys}		0.06 x V_{DD}			mV
9	P	Input leakage current (Per pin) all input only pins	$\|I_{In}\|$	V_{In} = V_{DD} or V_{SS}	—	0.1	1	µA
10	P	Hi-Z (off-state) leakage current (per pin) all input/output	$\|I_{OZ}\|$	V_{In} = V_{DD} or V_{SS}	—	0.1	1	µA
11	P	Pullup resistors (or Pulldown[2] resistors when enabled)	R_{PU}, R_{PD}	5 V	20	45	65	kΩ
	C			3 V	20	45	65	
12	T	Input Capacitance, all pins	C_{In}		—	—	8	pF
13	D	RAM retention voltage	V_{RAM}		—	0.6	1.0	V

Appendix B
Timer Pulse-Width Modulator (TPMV2)

NOTE

> This chapter refers to S08TPM version 2, which applies to the 3M05C and older mask sets of this device.)M74K and newer mask set devices use S08TPM version 3. If your device uses mask 0M74K or newer, please refer to Chapter 15, “Timer Pulse-Width Modulator (S08TPMV3) for information pertaining to that module.

The TPM uses one input/output (I/O) pin per channel, TPMxCHn where x is the TPM number (for example, 1 or 2) and n is the channel number (for example, 0–4). The TPM shares its I/O pins with general-purpose I/O port pins (refer to the Pins and Connections chapter for more information).

B.0.1 Features

The TPM has the following features:

- Each TPM may be configured for buffered, center-aligned pulse-width modulation (CPWM) on all channels
- Clock sources independently selectable per TPM (multiple TPMs device)
- Selectable clock sources (device dependent): bus clock, fixed system clock, external pin
- Clock prescaler taps for divide by 1, 2, 4, 8, 16, 32, 64, or 128
- 16-bit free-running or up/down (CPWM) count operation
- 16-bit modulus register to control counter range
- Timer system enable
- One interrupt per channel plus a terminal count interrupt for each TPM module (multiple TPMs device)
- Channel features:
  - Each channel may be input capture, output compare, or buffered edge-aligned PWM
  - Rising-edge, falling-edge, or any-edge input capture trigger
  - Set, clear, or toggle output compare action
  - Selectable polarity on PWM outputs

B.0.2 Block Diagram

Figure B-1 shows the structure of a TPM. Some MCUs include more than one TPM, with various numbers of channels.